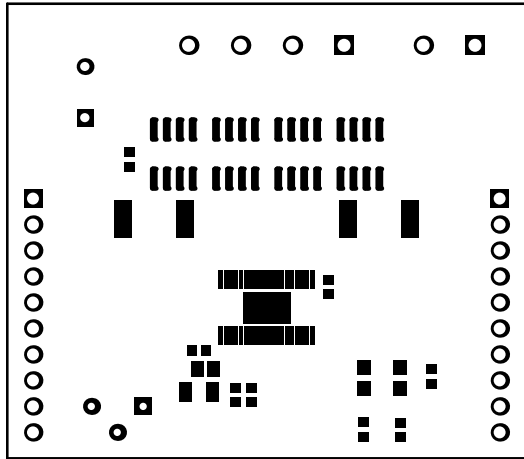
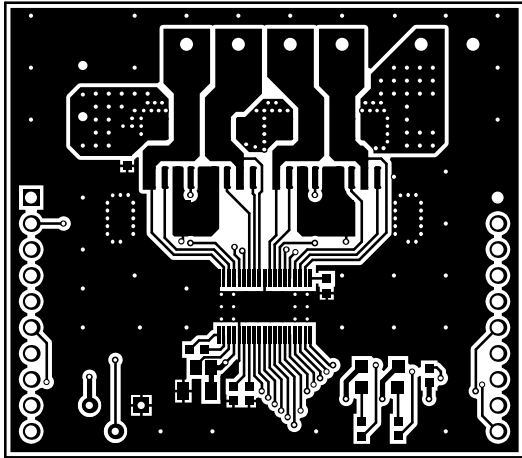


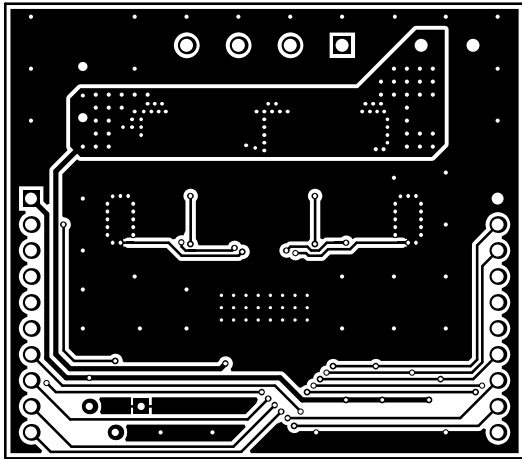
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRV8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay		
PLOT NAME = Top Overlay	GENERATED : 4/4/2014 10:28:17 AM	TEXAS INSTRUMENTS



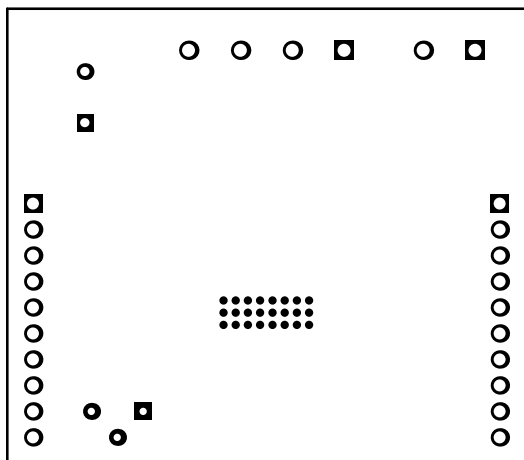
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder		
PLOT NAME = Top Solder Mask	GENERATED : 4/4/2014 10:28:18 AM	TEXAS INSTRUMENTS



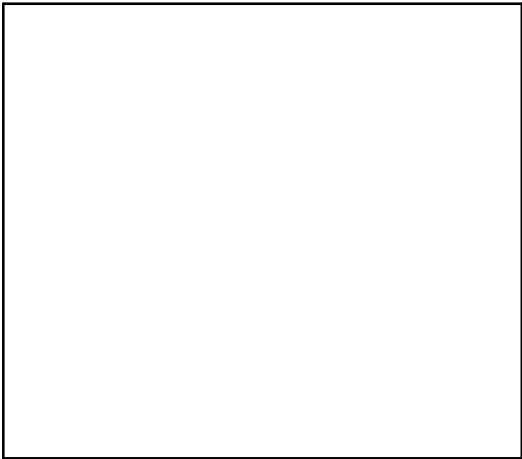
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer		
PLOT NAME = Top Layer	GENERATED : 4/4/2014 10:28:19 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer		
PLOT NAME = Bottom Layer	GENERATED : 4/4/2014 10:28:19 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/4/2014 10:28:20 AM	TEXAS INSTRUMENTS

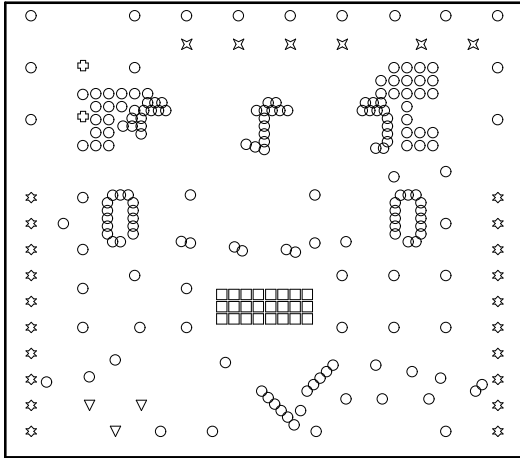


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711 REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay		
PLOT NAME = Bottom Overlay	GENERATED : 4/4/2014 10:28:21 AM	TEXAS INSTRUMENTS

Layer Stack Up Detail for: BOOST-DRV8711.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	<.GTS>		Solder Resist
Top Layer	<.GTL>	2.8mil	FR-4
Bottom Layer	<.GBL>	2.8mil	
Bottom Solder Mask	<.GBS>		Solder Resist

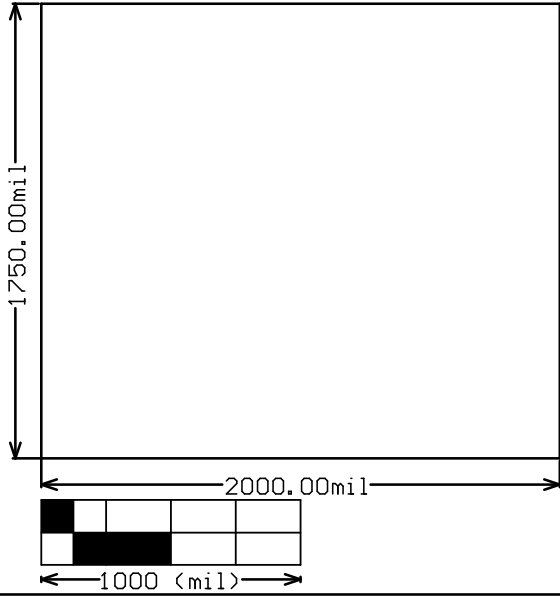
*Special Note: RED Solder Resist, TI BoosterPack



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	24	13mil (0.33mm)	PTH	Round
○	179	15mil (0.381mm)	PTH	Round
▽	3	28mil (0.711mm)	PTH	Round
⊕	2	35.433mil (0.9mm)	PTH	Round
✱	20	45.276mil (1.15mm)	PTH	Round
✕	6	49.213mil (1.25mm)	PTH	Round
	234 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRV8711	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/4/2014	10:28:21 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BOOST-DRU8711	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/4/2014	10:28:22 AM	TEXAS INSTRUMENTS

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